# Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays  
**Marketing Name / Model**  
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>HP Z32 4K UHD Display</th>
</tr>
</thead>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm IF BD, LED driver BD, Power BD, Function key BD</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Power BD only (C805)</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>USB cable, Display cable, Power cord</td>
<td>3</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove cable from Display Head
2. Remove Stand Base From Display Head
3. Remove Rear cover Assy From Display Head
4. Remove Back cover From Display Head
5. Remove Bracket Assy From Display Head
6. Remove mid-cover from Display Head
7. Remove Hinge bracket
8. Disassemble Bracket ASSY
9. Disassemble Rear cover
10. Disassemble Stand ASSY
11. Dissemble Panel Assy

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP Pint Z32 Disassembly Process

- Steve Chou
- Mechanical Engineer
- September-7-2017
External Electric Cables Dissecting Process

1. Remove Cable From Display Head.
Remove Stand Base From Display Head

2. Pull the release button

3. Remove Stand Base From Display Head.
4. Remove Rear Cover From Display Head.
Remove Back cover from Display Head

5. Remove Back cover from display head
Remove Bracket Assy from head

6. Remove Bracket Assy from head

Remove AL tape and cable
Remove Mid-cover from head

7. Remove Mid-cover from head
Remove Hinge bracket from Head

Remove Screws

8. Remove Hinge bracket from head
Disassemble Bracket ASSY

1. Remove Screws
2. Remove cable
3. Remove Mylar
   Gasket and thermal pad
Disassemble Bracket ASSY

Remove heat sink screws

Remove screws

Remove screws
Disassemble Rear cover

Remove Screws

Remove Function key
Disassemble Stand ASSY

1. Remove 4 screws
2. Separate base-top cover
3. Remove screw
4. Separate base-bottom cover
5. Remove screw and rubber
Disassemble Stand ASSY

1. Remove screw
2. Separate VESA cover
Disassemble Stand ASSY

1. Remove screw
2. Separate
3. Lift rear cover
4. Remove screw
5. Remove screw and lift front cover
Disassemble Panel ASSY

Method of LCM disassembly on LM315WR1-SSA1

Step 1: Loosen the Screw (5 Points)
Step 2: Remove C/Shield

Step 3: Remove Black Tape (8 ea) and LED FFC (2 ea)

Step 4: Insert Needle Tool

Step 5: Remove Sealing Ass’y

Step 6: Remove Control-PCB

Step 7: Remove Optical material (Sheet 4 ea + LGP + Reflector)

Step 8: Remove holders from each down side corner

Bare LCM
Disassemble Panel ASSY

Method of LCM disassembly on LM315WR1-SSA1

Step 8: Separate LED 2ea from C/Bottom